ASSOCIATION CONNECTING ELEGTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowelevel parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.											
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute										als and Mfg Information					
Supplier Informa	ation															
Company name*	Company un	Company unique ID			Unique ID Authority					Response Date*						
onsemi												2025-06-04				
Contact Name	Title - Contact			I	Phone - Contact*					Email - Contact*						
Product-Env-Stewar	rds	Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com					
uthorized Represen	ntative*	Title - Representative			I	Phone - Representative*				Email - Representative*						
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Requester	Item Number Mfr Item		em Number Mfr Item Name				Effective Dat	te Versio	Version Man		Manufacturing Site		/eight	.* U	OM	Unit Type
		NC7WZ02L8X- L22185 UHS Dual 2-		UHS Dual 2-Inpu	put NOR		2025-06-04		7	TH2		3	3.4562 mg		g	Each
Ianufacturing I	Proccess Information							·								
Terminal F	l Plating / Grid Array Material		Terminal Base Alloy		-STD-020 MSL Rating		Peak Process Body Temperature		re Max Time at Peak Temper		Temperatu	ture Number of Reflow Cycles		es		
Precious n Sn)	Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		CU Alloy 1		1		260		С		30 seco		ls 3	;		
Comments																
vel 1 - maximum tii	me at peak temperature d	uring sol	dering is 10-3	0 seconds												
	on regarding material com															

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.1476	mg	Supplier	Silicon (Si)	7440-21-3		0.1476	mg
Die Attach Epoxy	0.0154	mg		Epoxy resin	proprietary data		0.01	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		0.0054	mg
Lead Frame	1.0344	mg	Supplier	Magnesium (Mg)	7439-95-4		0.0018	mg
			Supplier	Silicon (Si)	7440-21-3		0.0077	mg
			В	Nickel (Ni)	7440-02-0		0.0336	mg
			Supplier	Copper (Cu)	7440-50-8		0.9914	mg
Mold Compound-Black	2.225	mg	Supplier	Carbon Black (C)	1333-86-4		0.0111	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		1.958	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		0.1446	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.1112	mg
Plating	0.0146	mg	Supplier	Palladium (Pd)	7440-05-3		0.0011	mg
			В	Nickel (Ni)	7440-02-0		0.0133	mg
			Supplier	Gold (Au)	7440-57-5		0.0002	mg
Wire Bond - Au	0.0192	mg	Supplier	Gold (Au)	7440-57-5		0.0192	mg